



(a) Plated Copper

(b) Copper Damascene Process

Figure 7.18 - Plated copper and copper Damascene process steps. (a) Mask openings are defined over seed layer and copper is plated in the opening. A nonplanar structure results after plating mask removal. (b) A seed layer is deposited over the patterned insulator, and copper is plated over the entire structure. A planar surface results after the excess copper is lapped away.